

N-Channel Super Junction Power MOSFET $\, \mathrm{I\!V} \,$

General Description

The series of devices use advanced trench gate super junction technology and design to provide ultra-low Rds(ON) and low gate charge and With a rapid recovery body diode. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, industrial power applications, Fast charger, new energy vehicle charging pile, on-board OBC etc.

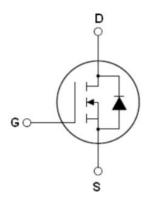
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- New technology for high voltage device
- ●Ultra low on-resistance and ultra low conduction losses
- Ultra Low Gate Charge cause lower driving requirements
- Diode reverse recovery speed is super fast
- ●100% Avalanche Tested and 100% Trr Tested
- High reliability
- ●ROHS compliant

Application

- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)
- On-board charger(OBC)

V _{DS, min@Tjmax}	650	V
RDS(ON)TYP.	23	mΩ
I_D	73	Α
Qg	135	nC



♦ Intrinsic fast-recovery body diode

Schematic diagram

Package Marking And Ordering Information

Device	Device Package	Marking	
NCE60NF031T	TO-247	NCE60NF031T	



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Table 1. Absolute Maximum Ratings (T_c=25℃)

Parameter	Symbol	Value	Unit
Drain-Source Voltage (VGS=0V)	V _{DS}	600	V
Gate-Source Voltage (VDS=0V) ,AC (f>1 Hz)	Vgs	±30	V
Gate-Source Voltage (VDS=0V) ,DC	Vgs	±20	V
Continuous Drain Current at Tc=25°C	I _{D (DC)}	73	А
Continuous Drain Current at Tc=100°C	I _{D (DC)}	51	А
Pulsed drain current (Note 1)	I _{DM (pluse)}	219	A
Maximum Power Dissipation(Tc=25℃)	PD	490	W
Derate above 25°C		3.2	W/°C
Single pulse avalanche energy (Note 2)	Eas	484	mJ
Single pulse avalanche current (Note 2)	I _{AS}	11	А
Repetitive Avalanche energy ,t _{AR} limited by T _{jmax} (Note 1)	E _{AR}	0.9	mJ



NCE60NF031T

preview

Reverse diode dv/dt, $V_{DS} \le 480 \text{ V,I}_{SD} < I_{D}$	dv/dt	50	V/ns
Drain Source voltage slope,V _{DS} ≤480 V	dv/dt	50	V/ns
Operating Junction and Storage Temperature Range	T_{J}, T_{STG}	-55+175	°C

Table 2. Thermal Characteristic

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case (Maximum)	R _{thJC}	0.31	°C /W
Thermal Resistance, Junction-to-Ambient (Maximum)	R _{thJA}	62	°C /W

Table 3. Electrical Characteristics (TA=25°Cunless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
On/off states						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =1mA	600			V
Zero Gate Voltage Drain Current(Tc=25°ℂ)	I _{DSS}	V _{DS} =600V,V _{GS} =0V			5	μA
Zero Gate Voltage Drain Current(Tc=125℃)	I _{DSS}	V _{DS} =600V,V _{GS} =0V			400	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V			±200	nA
Gate Threshold Voltage	V _{GS(th)}	VDS=VGS,ID=3mA	3	4	5	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =37A		23	31	mΩ
Dynamic Characteristics				•		
Gate Resistance	Rg	F=1MHZ, D-S short		3.5		Ω
Input Capacitance	C _{lss}	\/DC_E0\/\/CC_0\/		8000		pF
Output Capacitance	Coss	VDS=50V,VGS=0V, F=1MKHz		249		pF
Reverse Transfer Capacitance	Crss	Γ- ΠVINΠZ		15		pF
Total Gate Charge	Qg			135	145	nC
Gate-Source Charge	Qgs	\/ -400\/ -404 \/ -10\/		54		nC
Gate-Drain Charge	Q _{gd}	V _{DS} =400V,I _D =40A,V _{GS} =10V		46		nC
Gate plateau voltage	Vgp			7		V
Switching times						
Turn-on Delay Time	t _{d(on)}			55		nS
Turn-on Rise Time	t _r	V_{DD} =380 V , I_{D} =40 A ,		16		nS
Turn-Off Delay Time	$t_{d(off)}$	R_G =4 Ω , V_{GS} =10 V		125		nS
Turn-Off Fall Time	t _f			11		nS
Source- Drain Diode Characteristics						
Source-drain current(Body Diode)	I _{SD}	T =25°C			73	Α
Pulsed-Source-drain current(Body Diode)	I _{SDM}	T _C =25°C			219	Α
Forward on voltage	V _{SD}	Tj=25°C,I _{SD} =73A,V _{GS} =0V		1.0	1.2	V
Reverse Recovery Time	t _{rr}	T:-05°C L 40A		170		nS
Reverse Recovery Charge	Q _{rr}	Tj=25°C,I _F 40A,		1.3		uC
Peak reverse recovery current	I _{rrm}	di/dt=100A/μs		15.5		Α

Notes: 1. Repetitive Rating: Pulse width limited by maximum junction temperature

2. Tj=25 $^{\circ}\text{C}$,VDD=50V,VG=10V, RG=25 Ω



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

Figure 1. Safe operating area

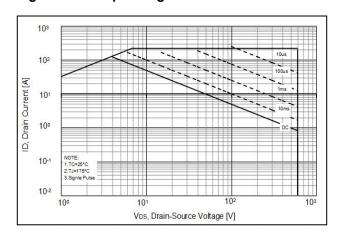


Figure 2. Source-Drain Diode Forward Voltage

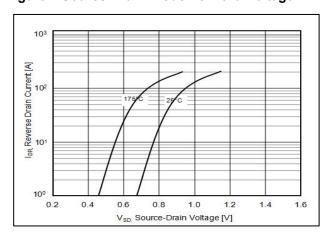


Figure 3. Output characteristics

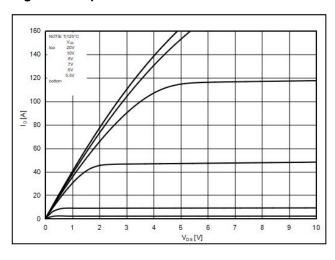


Figure 4. Transfer characteristics

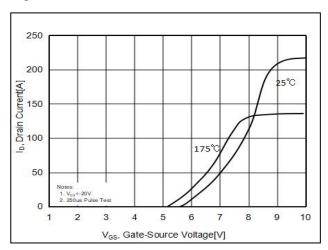


Figure 5. Static drain-source on resistance

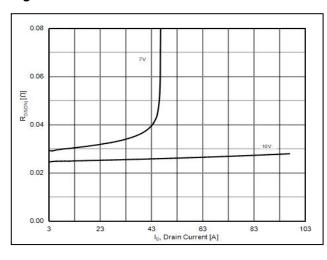
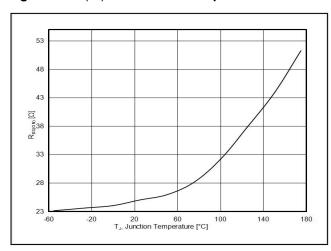


Figure 6. R_{DS(ON)} vs Junction Temperature



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Figure 7. BV_{DSS} vs Junction Temperature

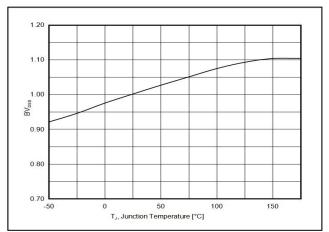


Figure 8. Maximum ID vs Junction Temperature

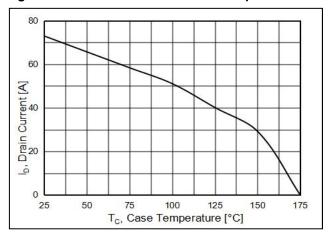


Figure 9. Gate charge waveforms

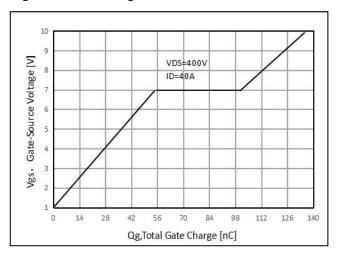
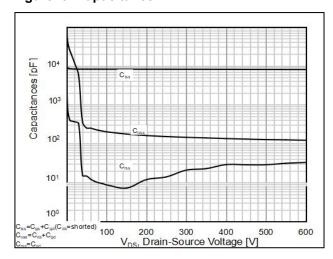


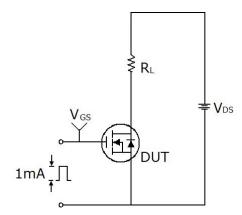
Figure 10. Capacitance

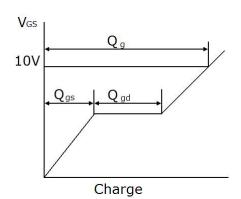




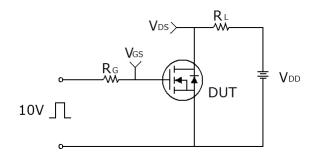
Test circuit

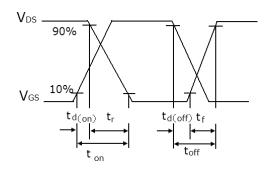
1) Gate charge test circuit & Waveform



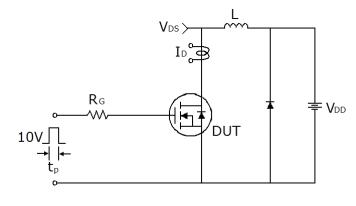


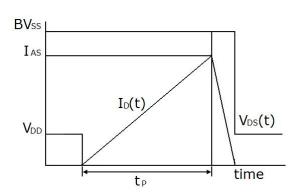
2) Switch Time Test Circuit:





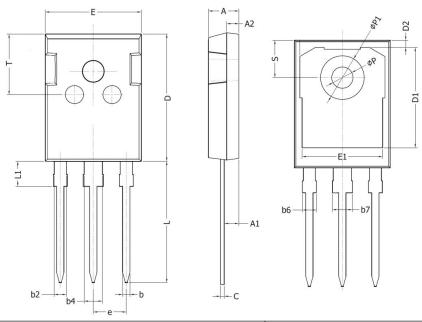
3) Unclamped Inductive Switching Test Circuit & Waveforms







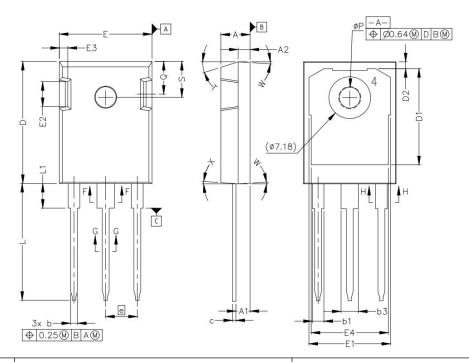
TO-247 (P) Package Information



0	Dimensions	Dimensions In Millimeters		s In Inches
Symbol	Min.	Max.	Min.	Max.
Α	4.90	5.10	0.193	0.201
A1	2.31	2.51	0.091	0.099
A2	1.90	2.10	0.075	0.083
b	1.16	1.26	0.046	0.050
b2	1.96	2.06	0.077	0.081
b4	2.96	3.06	0.117	0.120
b6	-	2.25	-	0.089
b7	-	3.25	-	0.128
С	0.59	0.66	0.023	0.026
D	20.90	21.10	0.823	0.831
D1	16.25	16.85	0.640	0.663
D2	1.05	1.35	0.041	0.053
E	15.70	15.90	0.618	0.626
E1	13.10	13.50	0.516	0.531
е	5.436	BSC	0.214	BSC
L	19.80	20.10	0.780	0.791
L1	-	4.30	-	0.169
Р	3.40	3.60	0.134	0.142
P1	7.00	7.40	0.276	0.291
S	6.05	6.25	0.238	0.246
Т	9.80	10.20	0.386	0.402



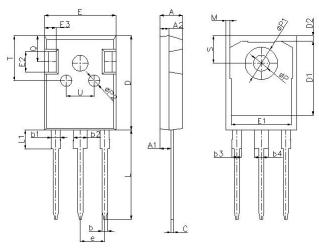
TO-247-B Package Information



Symbol	Dimensions	In Millimeters	Dimension	s In Inches
Symbol	Min.	Max.	Min.	Max.
A	4.83	5.21	0.190	0.205
A1	2.29	2.54	0.090	0.100
A2	1.91	2.16	0.075	0.085
b	1.07	1.33	0.042	0.052
b1	1.91	2.41	0.075	0.095
b3	2.87	3.38	0.113	0.133
С	0.55	0.68	0.022	0.027
D	20.80	21.10	0.819	0.831
D1	16.25	17.65	0.640	0.695
D2	0.95	1.25	0.037	0.049
E	15.75	16.13	0.620	0.635
E1	13.10	14.15	0.516	0.557
E2	3.68	5.10	0.145	0.201
E3	1.00	1.90	0.039	0.075
E4	12.38	13.43	0.487	0.529
е	5.44	BSC	0.214	I BSC
N	3.	00	0.1	118
L	19.81	20.32	0.780	0.800
L1	4.10	4.40	0.161	0.173
Р	3.51	3.65	0.138	0.144
Q	5.49	6.00	0.216	0.236
S	6.04	6.30	0.238	0.248



TO-247-E Package Information



O	Dimensions I	n Millimeters	Dimensions	In Inches
Symbol	Min.	Max.	Min.	Max.
А	4.90	5.10	0.193	0.201
A1	2.31	2.51	0.091	0.099
A2	1.90	2.10	0.075	0.083
b	1.16	1.26	0.046	0.050
b1	1.96	2.06	0.077	0.081
b2	2.96	3.06	0.117	0.120
b3	-	2.25	-	0.089
b4	-	3.25	-	0.128
С	0.59	0.66	0.023	0.026
D	20.90	21.10	0.823	0.831
D1	16.25	16.85	0.640	0.663
D2	1.05	1.35	0.041	0.053
E	15.70	15.90	0.618	0.626
E1	13.10	13.50	0.516	0.531
E2	4.40	4.60	0.173	0.181
E3	2.40	2.60	0.094	0.102
е	5.436	5.436BSC		SC
L	19.80	20.10	0.780	0.791
L1	-	4.30	-	0.169
М	0.35	0.95	0.014	0.037
Р	3.40	3.60	0.134	0.142
P1	7.00	7.40	0.276	0.291
P2	2.40	2.60	0.094	0.102
Q	5.60	6.00	0.220	0.236
S	6.05	6.25	0.238	0.246
Т	9.80	10.20	0.386	0.402
U	6.00	6.40	0.236	0.252



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